

INTERNATIONAL STANDARD

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**Field device integration (FDI) –
Part 103-1: Profiles – PROFIBUS**

**Intégration des appareils de terrain (FDI) –
Partie 103-1: Profils – PROFIBUS**



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IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
Fax: +41 22 919 03 00
info@iec.ch
www.iec.ch

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The text of this standard is based on the following documents:

CDV	Report on voting
65E/354/CDV	65E/417/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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FIELD DEVICE INTEGRATION (FDI) –

Part 103-1: Profiles – PROFIBUS

1 Scope

This part of IEC 62769 specifies an FDI profile of IEC 62769 for IEC 61784-1_CP 3/1 (PROFIBUS DP)¹ and IEC 61784-1_CP3/2 (PROFIBUS PA).

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61784-1, *Industrial communication networks – Profiles – Part 1: Fieldbus profiles*

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 62541-100:2015, *OPC unified architecture – Part 100: Device Interface*

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

NOTE 1 IEC 62769-2 is technical identical to FDI-2022.

IEC 62769-4, *Field Device Integration (FDI) – Part 4: FDI Packages*

NOTE 2 IEC 62769-4 is technically identical to FDI-2024.

IEC 62769-5, *Field Device Integration (FDI) – Part 5: FDI Information Model*

NOTE 3 IEC 62769-5 is technically identical to FDI-2025.

IEC 62769-7, *Field Device Integration (FDI) – Part 7: FDI Communication Devices*

NOTE 4 IEC 62769-7 is technically identical to FDI-2027.

PI Order No.: 2.122:2008, *Specification for PROFIBUS – Device Description and Device Integration – Volume 1: GSD, V5.1, July 2008: GSD*; available at <www.PROFIBUS.com>

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